

Proven Insight and Technical Expertise



Add Indium Corporation's Experts to Your Agenda Planner

Indium Corporation's leading technical experts are set to deliver and participate in a number of presentations and panel discussions throughout IPC APEX Expo.



"Innovative Low-Temperature Solder Alloy & Optimized Convection Reflow Oven Combination to Achieve up to 25% Energy Savings"

presented by Andreas Karch, Regional Technical Manager and Technologist-Advanced Applications

"Advancements in Solder Paste Printing: Cleaning Compatibility Assessment of Jettable and Screen-Printable Pastes for Complex Electronics Assemblies"

presented by Evan Griffith, Product Specialist



"Liquid Metal Paste High-Speed Dispensing for High-Volume Manufacturing"

presented by Miloš Lazić, Product Development Specialist

"The Attempt of Lower Temperature Soldering Process for Large Plastic Ball Grid Array Board-Level Assembly"

presented by HongWen Zhang, Ph.D., R&D Manager, Alloy Group



"Optimization of Photonic Soldering Processes for SIR Performance"

co-authored by Thuy Nguyen, Technical Support Engineer

"Liquid Metal Patterning for Electronic Circuits and Thermal Management"

co-authored by Miloš Lazić, Product Development Specialist, and Jon Major, Associate Director ESM Product Management



Panel Discussion: "PCBA Reliability and Test for EV Applications"

featuring Dave Sbiroli, Principal Engineer, Global Accounts Technical Manager

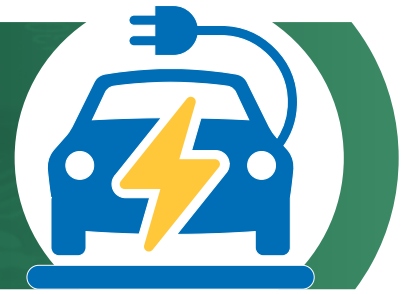
Date	Title	Team Member
9-April	Innovative Low-Temperature Solder Alloy & Optimized Convection Reflow Oven Combination to Achieve up to 25% Energy Savings	Andreas Karch
10-April	Advancements in Solder Paste Printing: Cleaning Compatibility Assessment of Jettable and Screen-Printable Pastes for Complex Electronics Assemblies	Evan Griffith
10-April	Liquid Metal Paste High-Speed Dispensing for High-Volume Manufacturing	Miloš Lazić
10-April	The Attempt of Lower Temperature Soldering Process for Large Plastic Ball Grid Array Board-Level Assembly	Dr. HongWen Zhang
10-April	Optimization of Photonic Soldering Processes for SIR Performance	Thuy Nguyen
10-April	Liquid Metal Patterning for Electronic Circuits and Thermal Management	Miloš Lazić Jon Major
11-April	Panel Discussion: PCBA Reliability and Test for EV Applications	Dave Sbiroli

Learn more: www.indium.com

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Driving e-Mobility: Rel-ion™ Technical Webinars series will address a range of topics beneficial to anyone with technical involvement or interest in electric vehicles and the automotive industry.



EV InSIDER LIVE series sheds light on the most pressing issues from across the dynamic and rapidly evolving electric vehicle landscape.



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